

## OT2-SN63-T3

Rev: 15.2

Date	2021.06.28
Language	English
SDS	950707



## SUMMARY

SnPb - Premium latest technology No-Clean solder paste - Halide/Halogen free

PASTE	OT2-SN63-T3
<b>PROCESS</b>	
No-Clean process	9
Post-solder cleaning	9

INDUSTRY APPLICATION	
Standard electronics	9
Industrial electronics	9
Hi-Rel electronics (automotive)	9

PROCESS CAPABILITY	
Squeegee	9
ProFlow	TBD
Pb-free Profile Air, short	9
Pb-free Profile Air, long	9
Pb-free process N2	9
Vapor phase process	7
Shiny joint appearance	9
Cosmetic cleanliness	9
ICCT compatible	9
Conformal coating	8

Legend	
<i>Especially made for this purpose</i>	9 - 10
<i>Generally qualified for this purpose</i>	7 - 8
<i>Generally usable, but not the best choice</i>	5 - 6
<i>Generally not usable for this purpose</i>	3 - 4
<i>Wrong choice</i>	1 - 2

Check material compatibility with every process change!

Industrial chemical product.

Read MSDS before use.

Product contains SVHC substance Lead with more than 0,1 Mass%.

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CLASSIFICATION	
DIN-EN-29454-1: 1994	1.1.3.C
IPC-J-STD-004-A: 2004	ROL0
IPC-J-STD-005: 1995 (Powder)	T3
Particle size	[µm] 25-45

PROPERTIES		
Flux code	OT2	
Alloy Code	SN63	
Alloy composition	Sn63Pb37	
Liquidus	[°C]	183
Solidus	[°C]	183
Recommended peak temp.	[°C]	205-225
Acid number	[mg KOH/g]	142.9
Flux	[% w/w]	10.9
Residues	Colorless	
Tackiness Malcom TK1	JIS-Z-3284	[gf] @ 0h 90

TEST REPORTS			
IPC/ANSI-J-STD-005			Compliant
Certificate of Compliance			Website
RoHS Compliant			No
Application Note			EN/DE
Copper Mirror	IPC-TM-650 2.3.32		Pass
Halides	IPC-TM-650 2.3.33	[Silver Chromate]	Pass
Halide	IPC-TM-650 2.3.35.1	[Fluoride by Spot]	Pass
Copper Corrosion	IPC-TM-650 2.6.15		Pass
SIR	IPC-TM-650 2.6.3.3		Pass
ECM	IPC-TM-650 2.6.14.1		Pass

PACKAGING AND STORAGE		
Packaging jar	PP [g]	500
Packaging cartridge	HDPE [g]	650
Packaging cartridge	HDPE [g]	1300
Packaging Cassette Pro-Flow	[g]	800
Minimum shelf-life in months	4-10 °C	5